onsemi

MOSFET - Power, Single P-Channel -40 V, 9.5 mΩ, -77 A NVMFS9D6P04M8L

Features

- Small Footprint for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- NVMFWS9D6P04M8L Wettable Flanks Product
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR–Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	-40	V
Gate-to-Source Voltage	Gate-to-Source Voltage			±20	V
Continuous Drain		$T_{C} = 25^{\circ}C$	۱ _D	-77.0	А
Current R _{θJC} (Notes 1, 2, 4)	Steady	$T_{C} = 100^{\circ}C$		-54.4	
Power Dissipation	State	T _C = 25°C	PD	75	W
R _{θJC} (Notes 1, 2)		T _C = 100°C		38	
Continuous Drain		T _A = 25°C	۱ _D	-17.1	А
Current R _{θJA} (Notes 1, 3, 4)	Steady	T _A = 100°C		-12.1	
Power Dissipation			PD	3.7	W
R _{θJA} (Notes 1, 3)		T _A = 100°C		1.8	
Pulsed Drain Current	$T_A = 25^{\circ}C$, $t_p = 10 \ \mu s$		I _{DM}	450	А
Operating Junction and Storage Temperature Range		T _J , T _{stg}	–55 to +175	°C	
Source Current (Body Diode)		۱ _S	-62	А	
Single Pulse Drain-to-Source Avalanche Energy ($I_{L(pk)} = -8.5 A$)		E _{AS}	259	mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		ΤL	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS (Note 1)

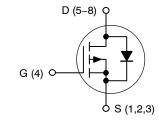
Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Drain) (Notes 1, 2, 4)	$R_{ extsf{ heta}JC}$	2	°C/W
Junction-to-Ambient - Steady State (Note 3)	$R_{\theta JA}$	40.7	

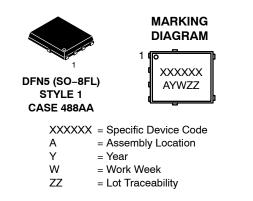
1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

- Assumes heat-sink sufficiently large to maintain constant case temperature independent of device power.
- 3. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 4. Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX
-40 V	9.5 mΩ @ −10 V	-77 A
	13.8 mΩ @ –4.5 V	

P-Channel MOSFET





ORDERING INFORMATION

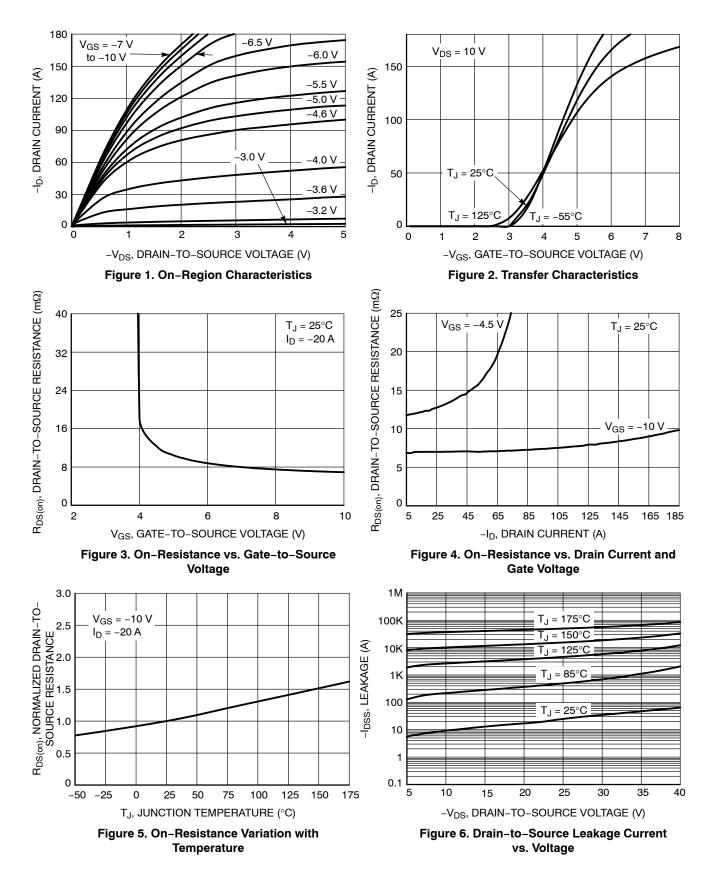
See detailed ordering, marking and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = $25^{\circ}C$ unless otherwise noted)

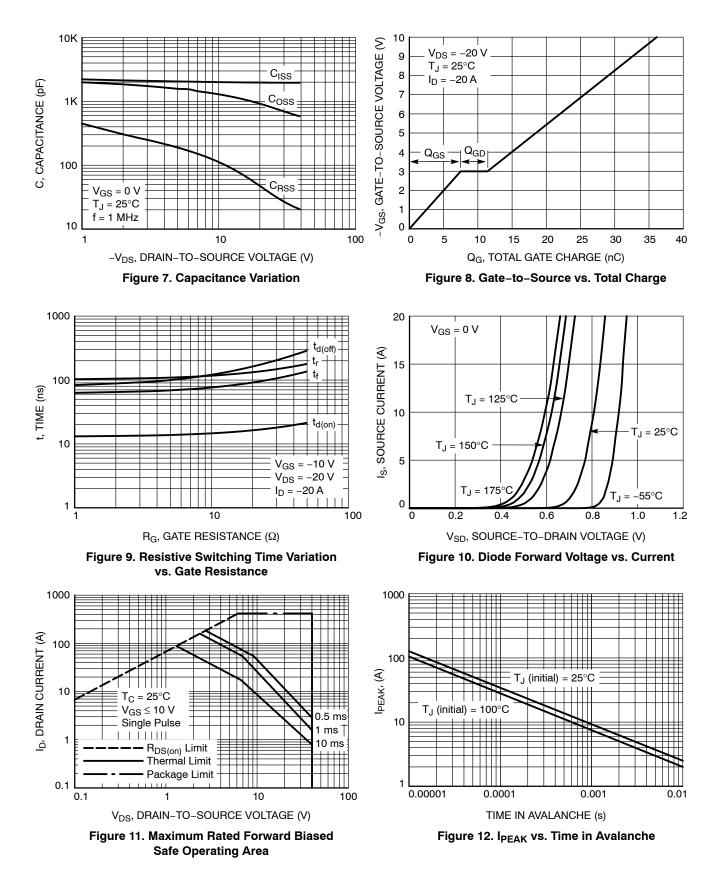
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = -250 \ \mu\text{A}$		-40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				21		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = -40 V	T _J = 25°C T _J = 125°C			-1.0 -1000	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS}				±100	nA
ON CHARACTERISTICS (Note 5)	400						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = -580 μA		-1.0		-2.4	V
Negative Threshold Temperature Co- efficient	V _{GS(TH)} /T _J				-5.1		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = -10 V, I	_D = -20 A		7.15	9.5	mΩ
		V _{GS} = -4.5 V, I	_D = -10 A		10.4	13.8	
Forward Transconductance	9 _{FS}	V _{DS} = -1.5 V, I	_D = -15 A		36		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{iss}				2002		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 V, f = V_{CS} = -2$	1.0 MHz,		935		1
Reverse Transfer Capacitance	C _{rss}	V _{DS} = -20 V			43		1
Total Gate Charge	Q _{G(TOT)}	V _{DS} = -20 V,	V_{GS} = -4.5 V		15.04		nC
		$I_{\rm D} = -20 \text{A}$ $V_{\rm GS} = -10 \text{V}$		14.47			
Threshold Gate Charge	Q _{G(TH)}	$V_{GS} = -10 \text{ V}, V_{DS} = -20 \text{ V},$ $I_D = -20 \text{ A}$			4.27		nC
Gate-to-Source Charge	Q _{GS}				11.94		
Gate-to-Drain Charge	Q _{GD}				12.83		
Plateau Voltage	V _{GP}				3.63		V
SWITCHING CHARACTERISTICS, VG	is = -4.5 V (Note	6)					
Turn-On Delay Time	t _{d(on)}				13.1		ns
Rise Time	t _r	VGS = -4.5 V. Vr	s = −20 V.		103		
Turn-Off Delay Time	t _{d(off)}	$\label{eq:VGS} \begin{array}{l} V_{GS} = -4.5 \text{ V}, \ V_{DS} = -20 \text{ V}, \\ I_{D} = -20 \text{ A}, \ R_{G} = 2.5 \ \Omega \end{array}$			83.3		
Fall Time	t _f				63.0		
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	V _{SD}	$V_{GS} = 0 V,$	$T_J = 25^{\circ}C$		-0.86	-1.25	V
		I _S = -20 A T _J = 125°C		-0.74		1	
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _S /dt = 100 A/µs, I _S = -20 A			54.6		ns
Charge Time	t _a				34.9		
Discharge Time	t _b				19.7		1
Reverse Recovery Charge	Q _{RR}				97.9		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 5. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%. 6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



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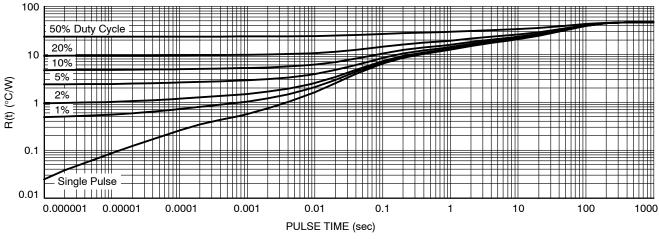


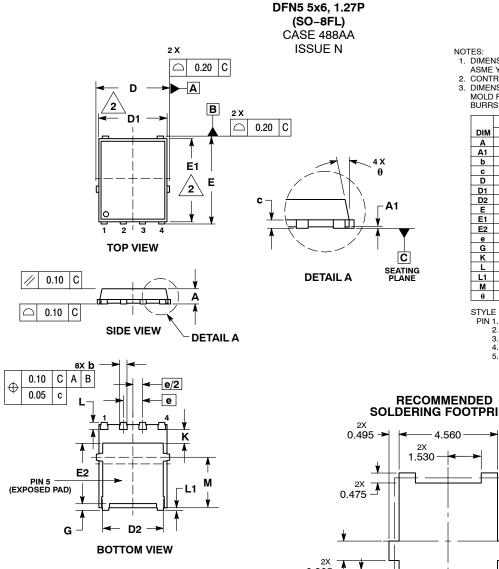
Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVMFS9D6P04M8LT1G	V9D6PL	DFNW5 (Pb–Free)	1500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

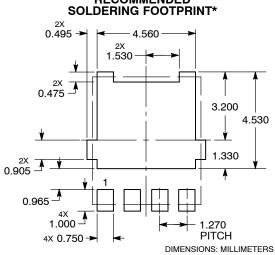
PACKAGE DIMENSIONS



- NOTES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION DI AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
с	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
Е	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е	1.27 BSC			
G	0.51	0.575	0.71	
ĸ	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
М	3.00	3.40	3.80	
θ	0 °		12 °	

STYLE 1: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN



*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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